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April 2000 Revised November 2000

#### 74LVTH652

## Low Voltage Octal Transceiver/Register with 3-STATE Outputs

#### **General Description**

The LVTH652 consists of bus transceiver circuits with D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes to HIGH logic level. Output Enable pins (OEAB, OEBA) are provided to control the transceiver function. (See Functional Description).

The LVTH652 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

This octal transceiver/register is designed for low-voltage (3.3V)  $V_{CC}$  applications, but with the capability to provide a TTL interface to a 5V environment. The LVTH652 is fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

#### **Features**

- $\blacksquare$  Input and output interface capability to systems at 5V  $V_{CC}$
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Functionally compatible with the 74 series 652
- Latch-up performance exceeds 500 mA
- ESD performance:

Human-body model > 2000V Machine model > 200V

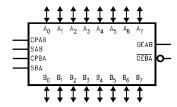
Charged-device model > 1000V

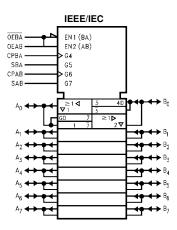
#### **Ordering Code:**

Order Number	Package Number	Package Description
74LVTH652WM	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74LVTH652MTC	MTC24	24-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

#### **Logic Symbols**





#### **Pin Descriptions**

#### **Connection Diagram**

Pin Names	Description
A <sub>0</sub> -A <sub>7</sub>	Data Register A Inputs/
	3-STATE Outputs
B <sub>0</sub> -B <sub>7</sub>	Data Register B Inputs/
	3-STATE Outputs
CPAB, CPBA	Clock Pulse Inputs
SAB, SBA	Select Inputs
OEAB, OEBA	Output Enable Inputs

CPAB —	1	24	− v <sub>cc</sub>
SAB -	2	23	— СРВ/
DEAB —	3	22	- SBA
A <sub>0</sub> —	4	21	— OEB
A <sub>1</sub> —	5	20	— B <sub>0</sub>
A <sub>2</sub> —	6	19	— В <sub>1</sub>
A <sub>3</sub> —	7	18	— в <sub>2</sub>
A4 —	8	17	— В <sub>3</sub>
A <sub>5</sub> —	9	16	— в₄
A <sub>6</sub> —	10	15	— В <sub>5</sub>
A <sub>7</sub> —	1.1	14	— В <sub>6</sub>
GND -	12	13	— В <sub>7</sub>

#### **Truth Table**

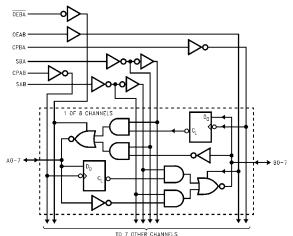
(Note 1)

		Inpu	ts			Inputs/	Outputs	On a watting a Manda
OEAB	OEBA	CPAB	СРВА	SAB	SBA	A <sub>0</sub> thru A <sub>7</sub>	B <sub>0</sub> thru B <sub>7</sub>	Operating Mode
L	Н	H or L	H or L	Χ	Χ	Input	Input	Isolation
L	Н	\	\	Χ	Х			Store A and B Data
Х	Н	\	H or L	Χ	Χ	Input	Not Specified	Store A, Hold B
Н	Н	\	\	Χ	Χ	Input	Output	Store A in Both Registers
L	Х	H or L	\	Χ	Х	Not Specified	Input	Hold A, Store B
L	L	\	\	Χ	Χ	Output	Input	Store B in Both Registers
L	L	Х	Х	Χ	L	Output	Input	Real-Time B Data to A Bus
L	L	Χ	H or L	Χ	Н			Store B Data to A Bus
Н	Н	Χ	Х	L	Х	Input	Output	Real-Time A Data to B Bus
Н	Н	H or L	Х	Н	Χ	1		Stored A Data to B Bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A Data to B Bus and Stored B Data to A Bus

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial  $\sim$  = LOW to HIGH Clock Transition

Note 1: The data output functions may be enabled or disabled by various signals at OEAB or OEBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.

#### **Logic Diagram**



TO 7 OTHER CHANNELS

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

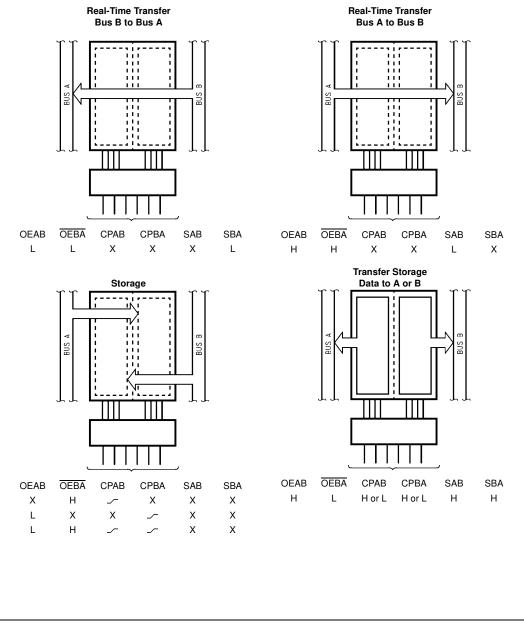
#### **Functional Description**

In the transceiver mode, data present at the HIGH impedance port may be stored in either the A or B register or both.

The select (SAB, SBA) controls can multiplex stored and real-time.

The examples below demonstrate the four fundamental bus-management functions that can be performed with the LVTH652.

Data on the A or B data bus, or both can be stored in the internal D-type flip-flop by LOW-to-HIGH transitions at the appropriate Clock Inputs (CPAB, CPBA) regardless of the Select or Output Enable Inputs. When SAB and SBA are in the real time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration each Output reinforces its Input. Thus when all other data sources to the two sets of bus lines are in a HIGH impedance state, each set of bus lines will remain at its last state.



#### Absolute Maximum Ratings(Note 2)

Symbol	Parameter	Value	Conditions	Units	
V <sub>CC</sub>	Supply Voltage	-0.5 to +4.6		V	
VI	DC Input Voltage	-0.5 to +7.0		V	
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V	
		-0.5 to +7.0	Output in HIGH or LOW State (Note 3)	V	
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA	
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA	
Io	DC Output Current	64	V <sub>O</sub> > V <sub>CC</sub> Output at HIGH State	mA	
		128	V <sub>O</sub> > V <sub>CC</sub> Output at LOW State	IIIA	
I <sub>CC</sub>	DC Supply Current per Supply Pin	±64		mA	
I <sub>GND</sub>	DC Ground Current per Ground Pin	±128		mA	
T <sub>STG</sub>	Storage Temperature	-65 to +150		°C	

#### **Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Units
V <sub>CC</sub>	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I <sub>OH</sub>	HIGH Level Output Current		-32	mA
I <sub>OL</sub>	LOW Level Output Current		64	mA
T <sub>A</sub>	Free-Air Operating Temperature	-40	85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V

Note 2: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 3: I<sub>O</sub> Absolute Maximum Rating must be observed.

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Parameter		V <sub>CC</sub>	T <sub>A</sub> =-40°C	to +85°C		Conditions	
raiailletei	T drameter		Min	Max	Oilito	Conditions	
Input Clamp Diode Voltage		2.7		-1.2	V	I <sub>I</sub> = -18 mA	
Input HIGH Voltage		2.7-3.6	2.0			V <sub>O</sub> ≤ 0.1V or	
Input LOW Voltage		2.7-3.6		0.8	· ·	$V_O \ge V_{CC} - 0.1V$	
Output HIGH Voltage		2.7-3.6	V <sub>CC</sub> - 0.2		V	I <sub>OH</sub> = -100 μA	
		2.7	2.4		V	I <sub>OH</sub> = -8 mA	
		3.0	2.0		V	I <sub>OH</sub> = -32 mA	
Output LOW Voltage		2.7		0.2	V	$I_{OL} = 100 \mu A$	
		2.7		0.5	V	I <sub>OL</sub> = 24 mA	
		3.0		0.4	V	I <sub>OL</sub> = 16 mA	
		3.0		0.5	V	I <sub>OL</sub> = 32 mA	
		3.0		0.55	V	I <sub>OL</sub> = 64 mA	
Bushold Input Minimum Drive		3.0	75		μΑ	V <sub>I</sub> = 0.8V	
			-75		μΑ	V <sub>I</sub> = 2.0V	
Bushold Input Over-Drive Current to Change State		3.0	500		μΑ	(Note 4)	
			-500		μΑ	(Note 5)	
Input Current		3.6		10	μΑ	V <sub>I</sub> = 5.5V	
	Control Pins	3.6		±1	μΑ	V <sub>I</sub> = 0V or V <sub>CC</sub>	
	Data Dina	0.0		<b>-</b> 5	μΑ	$V_I = 0V$	
	Data Pins	3.0		1	μΑ	$V_I = V_{CC}$	
Power OFF Leakage Current		0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$	
Power Up/Down 3-STATE		0.15\/		1100		V <sub>O</sub> = 0.5V to 3.0V	
Output Current		0-1.50		±100	μΑ	$V_I = GND \text{ or } V_{CC}$	
3-STATE Output Leakage Curre	ent	3.6		-5	μΑ	$V_{O} = 0.0V$	
3-STATE Output Leakage Curre	ent	3.6		5	μΑ	V <sub>O</sub> = 3.6V	
3-STATE Output Leakage Curre	ent	3.6		10	μΑ	$V_{CC} < V_O \le 5.5V$	
Power Supply Current		3.6		0.19	mA	Outputs HIGH	
Power Supply Current		3.6		5	mA	A or B Port Outputs LOW	
Power Supply Current		3.6		0.19	mA	Outputs Disabled	
Power Supply Current		3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$	
						Outputs Disabled	
Increase in Power Supply Curre	nt	3.6		0.2	mA	One Input at V <sub>CC</sub> – 0.6V	
(Note 6)						Other Inputs at V <sub>CC</sub> or GND	
	Input HIGH Voltage Input LOW Voltage Output HIGH Voltage Output HIGH Voltage Output HIGH Voltage  Output LOW Voltage  Bushold Input Minimum Drive Bushold Input Over-Drive Current to Change State Input Current  Power Up/Down 3-STATE Output Current 3-STATE Output Leakage Curre 3-STATE Output Leakage Curre Power Supply Current Power Supply Current Power Supply Current Power Supply Current Increase in Power Supply Current	Input Clamp Diode Voltage Input HIGH Voltage Input LOW Voltage Output HIGH Voltage Output LOW Voltage  Output LOW Voltage  Bushold Input Minimum Drive  Bushold Input Over-Drive Current to Change State Input Current  Control Pins Data Pins  Power OFF Leakage Current Power Up/Down 3-STATE Output Current 3-STATE Output Leakage Current 3-STATE Output Leakage Current Power Supply Current Power Supply Current Power Supply Current Power Supply Current Increase in Power Supply Current	Input Clamp Diode Voltage   2.7     Input Clamp Diode Voltage   2.7     Input HIGH Voltage   2.7-3.6     Input LOW Voltage   2.7-3.6     Output HIGH Voltage   2.7-3.6     Output LOW Voltage   2.7     3.0   2.7     3.0   3.0     3.0   3.0     3.0     3.0   3.0     3.0	Input Clamp Diode Voltage   2.7	Name   Name	Input Clamp Diode Voltage   2.7	

Note 4: An external driver must source at least the specified current to switch from LOW-to-HIGH.

#### **Dynamic Switching Characteristics** (Note 7)

Symbol	Parameter	V <sub>CC</sub> T <sub>A</sub> = 25°C		Units	Conditions		
Symbol	Farameter	(V)	Min	Тур	Max	Units	$\textbf{C}_{\textbf{L}} = \textbf{50}~\text{pF},~\textbf{R}_{\textbf{L}} = \textbf{500}\Omega$
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3		0.8		V	(Note 8)
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>	3.3		-0.8		V	(Note 8)

Note 7: Characterized in SOIC package. Guaranteed parameter, but not tested.

Note 8: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

Note 5: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

 $<sup>\</sup>textbf{Note 6:} \ \text{This is the increase in supply current for each input that is at the specified voltage level rather than $V_{CC}$ or GND.}$ 

#### **AC Electrical Characteristics**

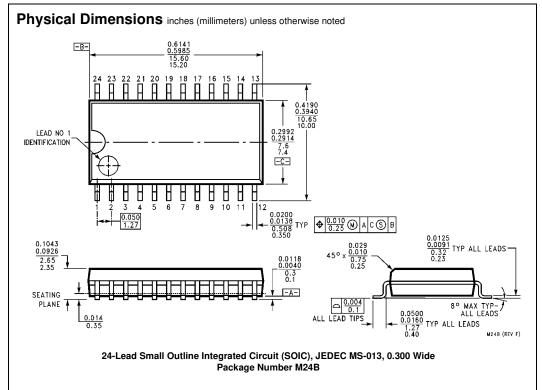
			T <sub>A</sub> = -40°C	C to +85°C					
Cumhal	Parameter			Unite					
Symbol	Parameter	V <sub>CC</sub> = 3.3	$3V \pm 0.3V$	V <sub>CC</sub> = 2.7V		Units			
			Min	Max	Min	Max			
f <sub>MAX</sub>	MAX Maximum Clock Frequency		150		150		MHz		
t <sub>PLH</sub>	Propagation Delay Data to Output		1.8	5.6	1.8	6.2			
t <sub>PHL</sub>	Clock to A or B		1.8	4.8	1.8	5.6	ns		
t <sub>PLH</sub>	Propagation Delay Data to Output		1.3	4.5	1.3	4.9			
t <sub>PHL</sub>	Data to A or B		1.3	4.6	1.3	5.2	ns		
t <sub>PLH</sub>	Propagation Delay Data to Output		1.5	5.5	1.5	6.4	ns		
t <sub>PHL</sub>	SBA or SAB to A or B		1.5	5.4	1.5	6.1	115		
t <sub>PZH</sub>	Output Enable Time		1.1	5.2	1.1	6.5			
$t_{PZL}$	OE to A		1.1	5.6	1.1	6.6	ns		
t <sub>PHZ</sub>	Output Disable Time		2.0	5.5	2.0	6.1			
t <sub>PLZ</sub>	OE to A		2.0	5.5	2.0	5.9	ns		
t <sub>PZH</sub>	Output Enable Time		1.3	4.9	1.3	5.7	ns		
t <sub>PZL</sub>	OE to B		1.3	5.3	1.3	5.8	115		
t <sub>PHZ</sub>	Output Disable Time		1.5	5.6	1.5	6.7			
t <sub>PLZ</sub>	OE to B		1.5	5.6	1.5	6.3	ns		
tw	Pulse Duration Clock	HIGH or LOW	3.3		3.3		ns		
t <sub>S</sub>	Setup Time Data H	HIGH before CP	1.2		1.5		ns		
	Data I	OW before CP	1.6		2.2				
t <sub>H</sub>	Hold Time Data I	HIGH or LOW after CP	0.8		0.8		ns		
toshl	Output to Output Skew			1.0		1.0	ns		
toslh	(Note 9)			1.0		1.0			

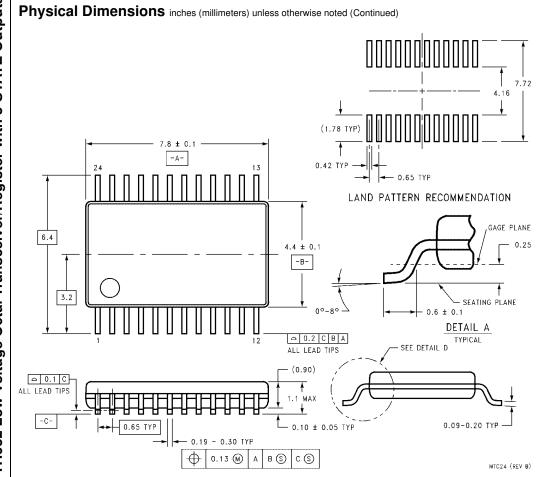
Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>).

#### Capacitance (Note 10)

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 0V$ , $V_I = 0V$ or $V_{CC}$	4	pF
C <sub>I/O</sub>	Input/Output Capacitance	$V_{CC} = 3.0V$ , $V_O = 0V$ or $V_{CC}$	8	pF

Note 10: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012.





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24-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC24

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